

MPI TS200-SE | 200 mm Manual Probe System with ShieldEnvironment™

Designed for accurate and reliable DC/CV and RF measurements at a wide temperature range

Microscope Mount and Movement

- Stable bridge for high quality optics
- Linear z lift for easy reconfiguration
- 50 x 50 mm linear XY movement

Probe Platen

- Stable and rigid design
- Rectangular adjustments for RF MicroPositioners
- Integrated probe platen air-cooling for max. thermal stability

RF Calibration

- 2 auxiliary chucks for calibration substrates
- Built-in ceramic for accurate calibration
- 1µm flatness for consistent contact quality

DC and RF MicroPositioners

- Supports up to 4 RF and 8 DC MicroPositioners
- Wide range of MicroPositioners available
- Dedicated probe arms for DC/CV and RF measurements

Unique Platen Lift

- Three discrete positions for contact, separation (300 µm) and safety loading 3 mm
- Safety lock function at loading position
- "Auto Contact" position with ±1 µm repeatability for consistent contact quality

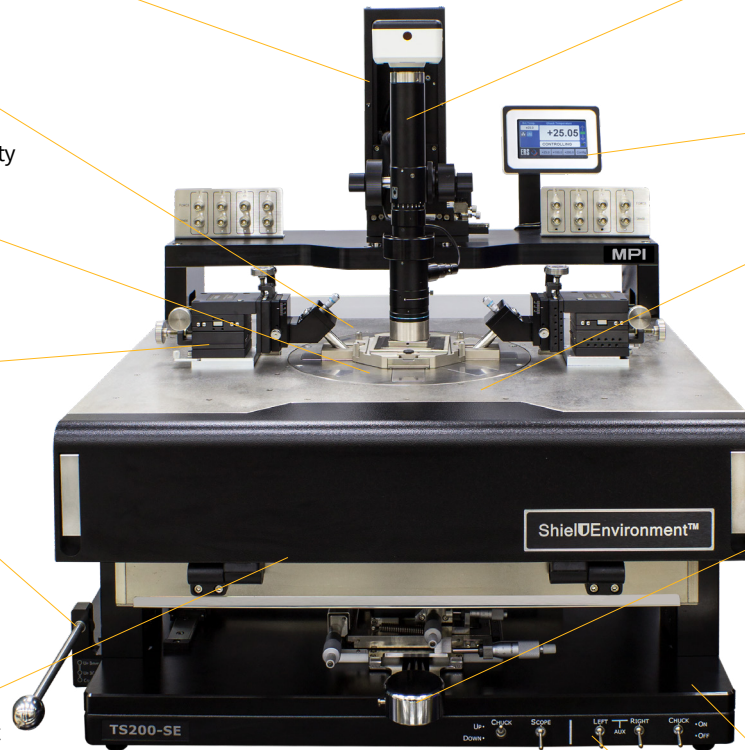
ShieldEnvironment™

- Excellent EMI and light-tight shielded test environment for ultra-low noise, low capacitance measurements
- Front door for manual loading of IC or wafers ShieldDCap™
- Consequent shielding and easy re-configuration
- Allows up to 4-port RF or up to 8-ports DC/Kelvin or a combination of those configurations
- Probe card version available
- Automated frontdoor on/off lock function for safety ice-free testing

- Vibration isolation table
- Vacuum pump and air compressor unit

Available Options

- Table with integrated rack for thermal controller, computer and keyboard push tray
- Dual monitor stand option
- Instrument shelf option



Microscope and Optics Options

- Various optics options available
- Single tube MPI SZ10, MZ12 with up to 12x zoom and 95 mm working distance
- HDMI cameras, monitor user interface without computer

Thermal Chuck Integration

- Full thermal chuck control over touchscreen display
- Easy operation and temperature feedback

Modular Chucks

- Various non-thermal or thermal chucks
- Choice of Triaxial or Coaxial connection
- Wide range of temperature up to 300 °C
- Field upgradable for reduced cost of ownership
- Easy switch between center and small wafer size control

Kelvin Interface

- Optional Kelvin interface for easy cable management

Chuck XYZ Stage Movement

- Unique puck controlled air bearing stage for quick single-handed operation
- 225 x 260 mm XY total stage movement
- 25 x 25 mm XY fine micrometer adjustment
- Resolution < 1.0 µm (0.04 mils) @ 500 µm/rev
- 20 mm Z load / unload stroke, pneumatically
- 5 mm fine Z, resolution < 1.0 µm (0.04 mils) @ 500 µm/rev
- ±5° Theta fine adjustment
- Extra wide Y-range for easy wafer loading

Ultra Footprint

- Designed for bench top use
- Comes with vibration absorber base
- Low profile design for maximum usability

Front Mounted Vacuum Control

- Easy access
- Clearly marked